

LMC6022 Low Power CMOS Dual Operational Amplifier

Check for Samples: [LMC6022](#)

FEATURES

- Specified for 100 k Ω and 5 k Ω loads
- High voltage gain: 120 dB
- Low offset voltage drift: 2.5 $\mu\text{V}/^\circ\text{C}$
- Ultra low input bias current: 40 fA
- Input common-mode range includes V^-
- Operating range from +5V to +15V supply
- Low distortion: 0.01% at 1 kHz
- Slew rate: 0.11 V/ μs
- Micropower operation: 0.5 mW

APPLICATIONS

- High-impedance buffer or preamplifier
- Current-to-voltage converter
- Long-term integrator
- Sample-and-hold circuit
- Peak detector
- Medical instrumentation
- Industrial controls

DESCRIPTION

The LMC6022 is a CMOS dual operational amplifier which can operate from either a single supply or dual supplies. Its performance features include an input common-mode range that reaches V^- , low input bias current, and voltage gain (into 100k and 5 k Ω loads) that is equal to or better than widely accepted bipolar equivalents, while the power supply requirement is less than 0.5 mW.

This chip is built with National's advanced Double-Poly Silicon-Gate CMOS process.

See the LMC6024 datasheet for a CMOS quad operational amplifier with these same features.

Connection Diagram

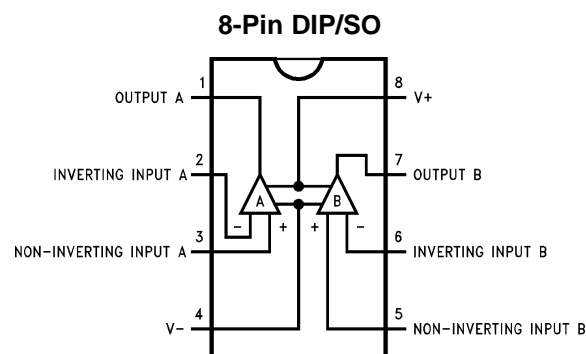


Figure 1. Top View

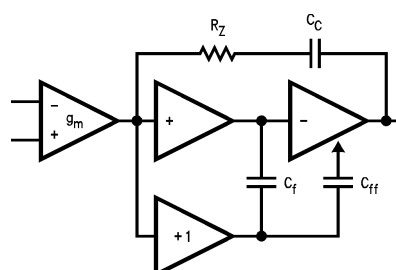


Figure 2. LMC6022 Circuit Topology (Each Amplifier)



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾

Differential Input Voltage	±Supply Voltage
Supply Voltage ($V^+ - V^-$)	16V
Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	-65°C to +150°C
Junction Temperature	150°C
ESD Tolerance (Note 4)	1000V
Voltage at Output/Input Pin	(V^+) +0.3V, (V^-) -0.3V
Current at Output Pin	±18 mA
Current at Power Supply Pin	35 mA
Power Dissipation	(2)
Current at Input Pin	±5 mA
Output Short Circuit to V^-	(3)
Output Short Circuit to V^+	(4)

- (1) Absolute Maximum Ratings indicate limits beyond which damage to component may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.
- (2) The maximum power dissipation is a function of $T_{J(max)}$, θ_{JA} and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(max)} - T_A)/\theta_{JA}$.
- (3) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature and/or multiple Op Amp shorts can result in exceeding the maximum allowed junction temperature of 150°C. Output currents in excess of ±30 mA over long term may adversely affect reliability.
- (4) Do not connect output to V^+ when V^+ is greater than 13V or reliability may be adversely affected.

Operating Ratings

Temperature Range	-40°C ≤ T_J ≤ +85°C
Supply Voltage Range	4.75V to 15.5V
Power Dissipation	(Note 10)
Thermal Resistance (θ_{JA}) ⁽¹⁾	
8-Pin DIP	101°C/W
8-Pin SO	165°C/W

- (1) All numbers apply for packages soldered directly into a PC board.

DC Electrical Characteristics

The following specifications apply for $V^+ = 5V$, $V^- = 0V$, $V_{CM} = 1.5V$, $V_O = 2.5V$, and $R_L = 1M$ unless otherwise noted.

Boldface limits apply at the temperature extremes; all other limits $T_J = 25^\circ C$.

Symbol	Parameter	Conditions		Typical ⁽¹⁾	LMC6022I	Units
					Limit ⁽²⁾	
V _{OS}	Input Offset Voltage			1	9	mV
					11	max
ΔV _{OS} /ΔT	Input Offset Voltage Average Drift			2.5		μV/°C
I _B	Input Bias Current			0.04		pA
					200	max
I _{OS}	Input Offset Current			0.01		pA
					100	max
R _{IN}	Input Resistance			>1		TeraΩ
CMRR	Common Mode Rejection Ratio	0V ≤ V _{CM} ≤ 12V V ⁺ = 15V		83	63	dB
					61	min
+PSRR	Positive Power Supply Rejection Ratio	5V ≤ V ⁺ ≤ 15V		83	63	dB
					61	min
−PSRR	Negative Power Supply Rejection Ratio	0V ≤ V [−] ≤ −10V		94	74	dB
					73	min
V _{CM}	Input Common-Mode Voltage Range	V ⁺ = 5V & 15V For CMRR ≥ 50 dB		−0.4	−0.1	V
					0	max
				V ⁺ − 1.9	V ⁺ − 2.3	V
					V⁺ − 2.5	min
A _V	Large Signal Voltage Gain	R _L = 100 kΩ ⁽³⁾	Sourcing	1000	200	V/mV
					100	min
			Sinking	500	90	V/mV
					40	min
		R _L = 5 kΩ ⁽³⁾	Sourcing	1000	100	V/mV
					75	min
			Sinking	250	50	V/mV
					20	min

(1) Typical values represent the most likely parametric norm.

(2) All limits are guaranteed by testing or correlation.

(3) $V^+ = 15V$, $V_{CM} = 7.5V$, and R_L connected to 7.5V. For Sourcing tests, $7.5V \leq V_O \leq 11.5V$. For Sinking tests, $2.5V \leq V_O \leq 7.5V$.

DC Electrical Characteristics (continued)

The following specifications apply for $V^+ = 5V$, $V^- = 0V$, $V_{CM} = 1.5V$, $V_O = 2.5V$, and $R_L = 1M$ unless otherwise noted.

Boldface limits apply at the temperature extremes; all other limits $T_J = 25^\circ C$.

Symbol	Parameter	Conditions	Typical ⁽¹⁾	LMC6022I	Units
				Limit ⁽²⁾	
V_O	Output Voltage Swing	$V^+ = 5V$ $R_L = 100\text{ k}\Omega$ to $2.5V$	4.987	4.40	V
				4.43	min
			0.004	0.06	V
				0.09	max
		$V^+ = 5V$ $R_L = 5\text{ k}\Omega$ to $2.5V$	4.940	4.20	V
				4.00	min
			0.040	0.25	V
				0.35	max
		$V^+ = 15V$ $R_L = 100\text{ k}\Omega$ to $7.5V$	14.970	14.00	V
				13.90	min
			0.007	0.06	V
				0.09	max
I_O	Output Current	$V^+ = 5V$ Sourcing, $V_O = 0V$ Sinking, $V_O = 5V$ ⁽⁴⁾	22	13	mA
				9	min
			21	13	mA
				9	min
		$V^+ = 15V$ Sourcing, $V_O = 0V$ Sinking, $V_O = 13V$ ⁽⁵⁾	40	23	mA
				15	min
			39	23	mA
				15	min
I_S	Supply Current	Both Amplifiers $V_O = 1.5V$	86	140	μA
				165	max

(4) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature and/or multiple Op Amp shorts can result in exceeding the maximum allowed junction temperature of $150^\circ C$. Output currents in excess of $\pm 30\text{ mA}$ over long term may adversely affect reliability.

(5) Do not connect output to V^+ when V^+ is greater than $13V$ or reliability may be adversely affected.

AC Electrical Characteristics

The following specifications apply for $V^+ = 5V$, $V^- = 0V$, $V_{CM} = 1.5V$, $V_O = 2.5V$, and $R_L = 1M$ unless otherwise noted.

Boldface limits apply at the temperature extremes; all other limits $T_J = 25^\circ C$.

Symbol	Parameter	Conditions	Typical (1)	LMC6022I	Units
				Limit ⁽²⁾	
SR	Slew Rate	⁽³⁾	0.11	0.05	V/ μs
				0.03	min
GBW	Gain-Bandwidth Product		0.35		MHz
ϕ_M	Phase Margin		50		Deg
G_M	Gain Margin		17		dB
	Amp-to-Amp Isolation	⁽⁴⁾	130		dB
e_n	Input-Referred Voltage Noise	$F = 1 \text{ kHz}$	42		nV/ \sqrt{Hz}
i_n	Input-Referred Current Noise	$F = 1 \text{ kHz}$	0.0002		pA/ \sqrt{Hz}

(1) Typical values represent the most likely parametric norm.

(2) All limits are guaranteed by testing or correlation.

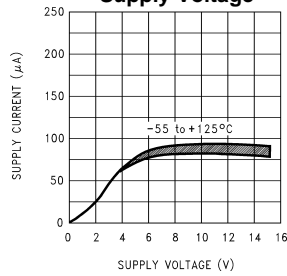
(3) $V^+ = 15V$. Connected as Voltage Follower with 10V step input. Number specified is the slower of the positive and negative slew rates.

(4) Input referred. $V^+ = 15V$ and $R_L = 100 \text{ k}\Omega$ connected to 7.5V. Each amp excited in turn with 1 kHz to produce $V_O = 13 V_{PP}$.

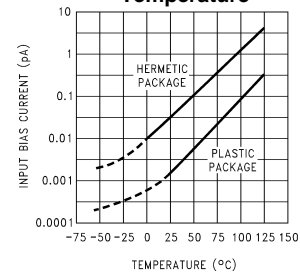
Typical Performance Characteristics

$V_S = \pm 7.5V$, $T_A = 25^\circ C$ unless otherwise specified

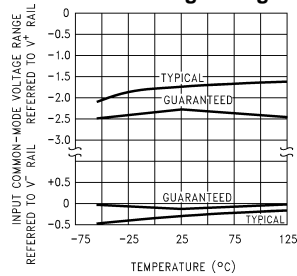
**Supply Current
vs.
Supply Voltage**



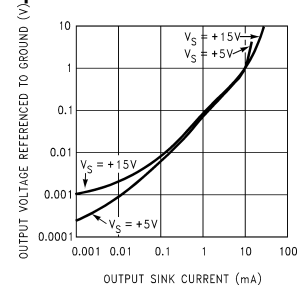
**Input Bias Current
vs.
Temperature**



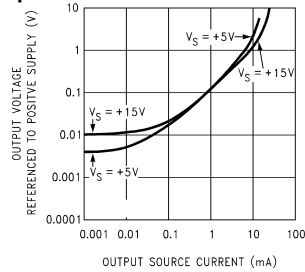
Input Common-Mode Voltage Range vs. Temperature



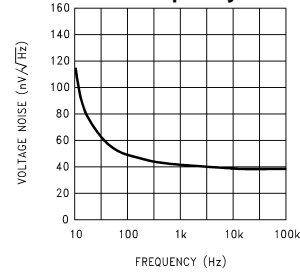
Output Characteristics Current Sinking



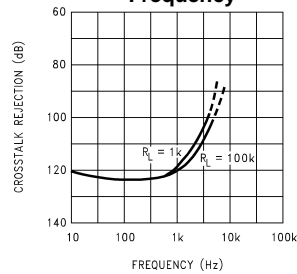
Output Characteristics Current Sourcing



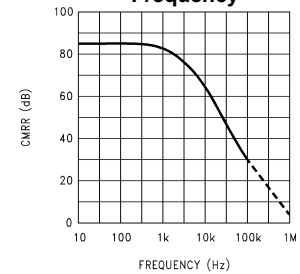
**Input Voltage Noise
vs.
Frequency**



**Crosstalk Rejection
vs.
Frequency**

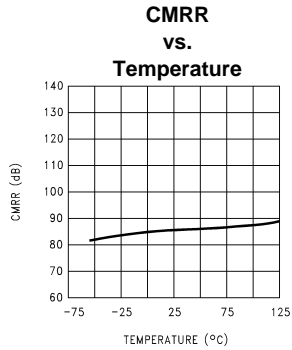


**CMRR
vs.
Frequency**

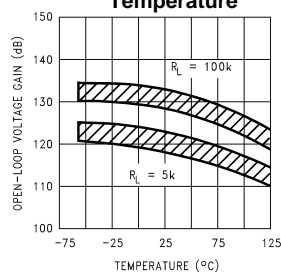


Typical Performance Characteristics (continued)

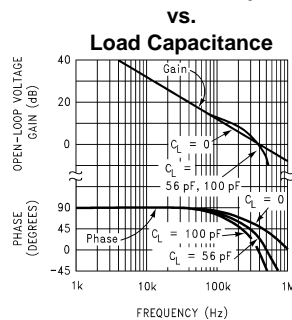
$V_S = \pm 7.5V$, $T_A = 25^\circ C$ unless otherwise specified



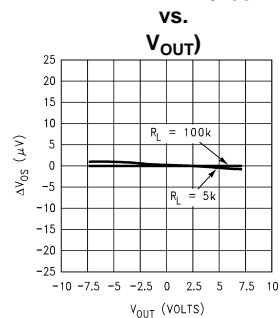
Open-Loop Voltage Gain **vs.** **Temperature**



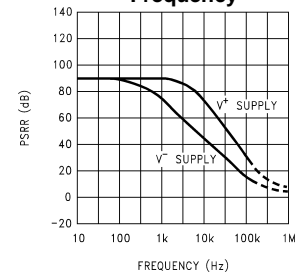
Gain and Phase Responses



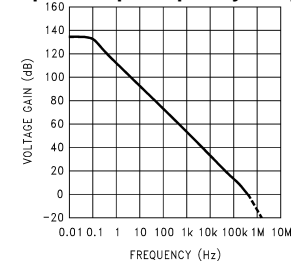
Gain Error (V_{OS})



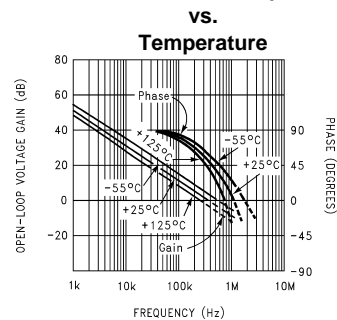
Power Supply Rejection Ratio **vs.** **Frequency**



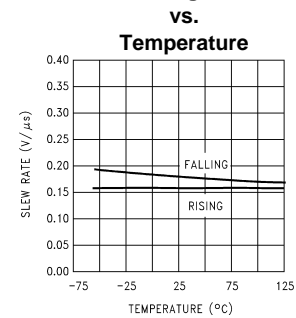
Open-Loop Frequency Response



Gain and Phase Responses



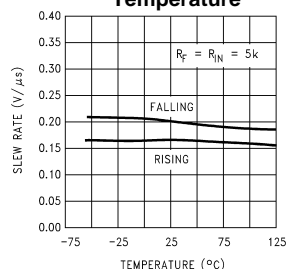
Non-Inverting Slew Rate



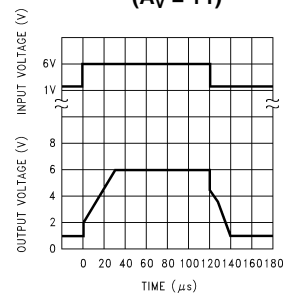
Typical Performance Characteristics (continued)

$V_S = \pm 7.5V$, $T_A = 25^\circ C$ unless otherwise specified

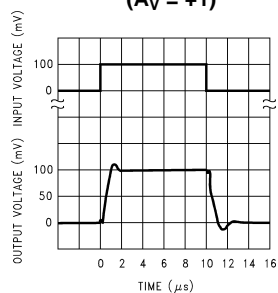
Inverting Slew Rate vs. Temperature



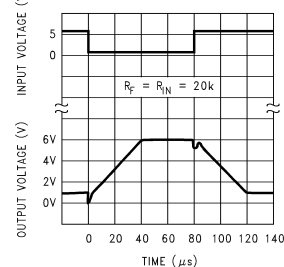
Large-Signal Pulse Non-Inverting Response ($A_V = +1$)



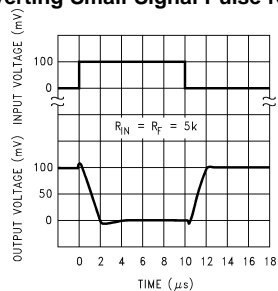
Non-Inverting Small Signal Pulse Response ($A_V = +1$)



Inverting Large-Signal Pulse Response

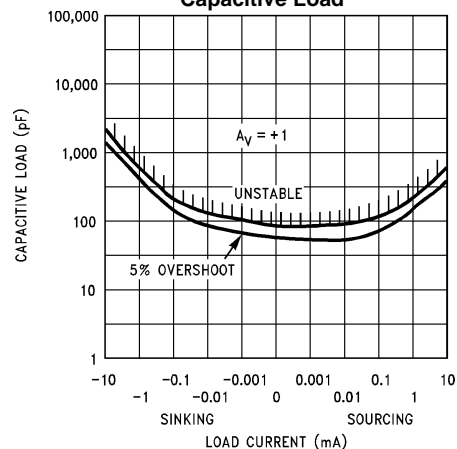


Inverting Small-Signal Pulse Response



Stability vs.

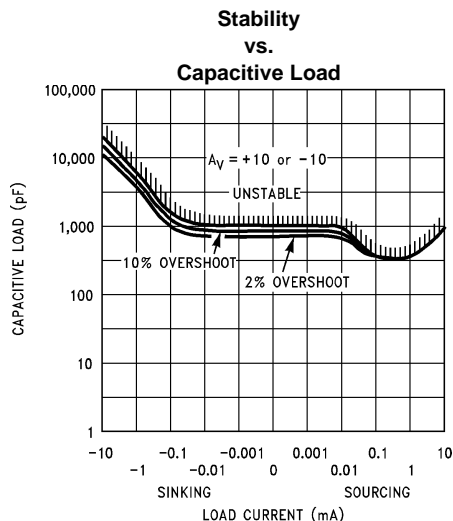
Capacitive Load



Note: Avoid resistive loads of less than 500Ω, as they may cause instability.

Typical Performance Characteristics (continued)

$V_S = \pm 7.5V$, $T_A = 25^\circ C$ unless otherwise specified



Application Hints

AMPLIFIER TOPOLOGY

The topology chosen for the LMC6022 is unconventional (compared to general-purpose op amps) in that the traditional unity-gain buffer output stage is not used; instead, the output is taken directly from the output of the integrator, to allow rail-to-rail output swing. Since the buffer traditionally delivers the power to the load, while maintaining high op amp gain and stability, and must withstand shorts to either rail, these tasks now fall to the integrator.

As a result of these demands, the integrator is a compound affair with an embedded gain stage that is doubly fed forward (via C_f and C_{ff}) by a dedicated unity-gain compensation driver. In addition, the output portion of the integrator is a push-pull configuration for delivering heavy loads. While sinking current the whole amplifier path consists of three gain stages with one stage fed forward, whereas while sourcing the path contains four gain stages with two fed forward.

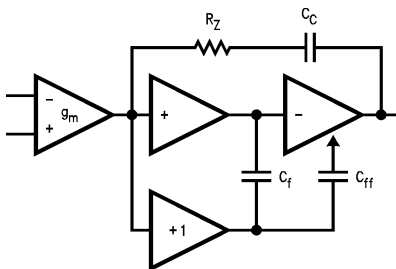


Figure 3. LMC6022 Circuit Topology (Each Amplifier)

The large signal voltage gain while sourcing is comparable to traditional bipolar op amps for load resistance of at least 5 k Ω . The gain while sinking is higher than most CMOS op amps, due to the additional gain stage; however, when driving load resistance of 5 k Ω or less, the gain will be reduced as indicated in the Electrical Characteristics. The op amp can drive load resistance as low as 500 Ω without instability.

COMPENSATING INPUT CAPACITANCE

Refer to the LMC660 or LMC662 datasheets to determine whether or not a feedback capacitor will be necessary for compensation and what the value of that capacitor would be.

CAPACITIVE LOAD TOLERANCE

Like many other op amps, the LMC6022 may oscillate when its applied load appears capacitive. The threshold of oscillation varies both with load and circuit gain. The configuration most sensitive to oscillation is a unity-gain follower. See the Typical Performance Characteristics.

The load capacitance interacts with the op amp's output resistance to create an additional pole. If this pole frequency is sufficiently low, it will degrade the op amp's phase margin so that the amplifier is no longer stable at low gains. The addition of a small resistor (50Ω to 100Ω) in series with the op amp's output, and a capacitor (5 pF to 10 pF) from inverting input to output pins, returns the phase margin to a safe value without interfering with lower-frequency circuit operation. Thus, larger values of capacitance can be tolerated without oscillation. Note that in all cases, the output will ring heavily when the load capacitance is near the threshold for oscillation.

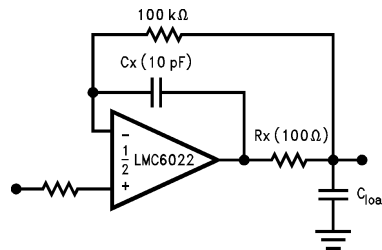


Figure 4. Rx, Cx Improve Capacitive Load Tolerance

Capacitive load driving capability is enhanced by using a pull up resistor to V^+ (Figure 5). Typically a pull up resistor conducting $50\ \mu\text{A}$ or more will significantly improve capacitive load responses. The value of the pull up resistor must be determined based on the current sinking capability of the amplifier with respect to the desired output swing. Open loop gain of the amplifier can also be affected by the pull up resistor (see Electrical Characteristics).

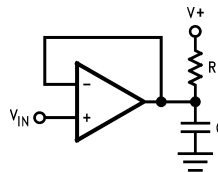


Figure 5. Compensating for Large Capacitive Loads with a Pull Up Resistor

PRINTED-CIRCUIT-BOARD LAYOUT FOR HIGH-IMPEDANCE WORK

It is generally recognized that any circuit which must operate with less than $1000\ \text{pA}$ of leakage current requires special layout of the PC board. When one wishes to take advantage of the ultra-low bias current of the LMC6022, typically less than $0.04\ \text{pA}$, it is essential to have an excellent layout. Fortunately, the techniques for obtaining low leakages are quite simple. First, the user must not ignore the surface leakage of the PC board, even though it may sometimes appear acceptably low, because under conditions of high humidity or dust or contamination, the surface leakage will be appreciable.

To minimize the effect of any surface leakage, lay out a ring of foil completely surrounding the LMC6022's inputs and the terminals of capacitors, diodes, conductors, resistors, relay terminals, etc. connected to the op-amp's inputs. See Figure 6. To have a significant effect, guard rings should be placed on both the top and bottom of the PC board. This PC foil must then be connected to a voltage which is at the same voltage as the amplifier inputs, since no leakage current can flow between two points at the same potential. For example, a PC board trace-to-pad resistance of $10^{12}\Omega$, which is normally considered a very large resistance, could leak $5\ \text{pA}$ if the trace were a 5V bus adjacent to the pad of an input. This would cause a 100 times degradation from the LMC6022's actual performance. However, if a guard ring is held within $5\ \text{mV}$ of the inputs, then even a resistance of $10^{11}\Omega$ would cause only $0.05\ \text{pA}$ of leakage current, or perhaps a minor (2:1) degradation of the amplifier's performance. See Figure 7, Figure 8, Figure 9 for typical connections of guard rings for standard op-amp configurations. If both inputs are active and at high impedance, the guard can be tied to ground and still provide some protection; see Figure 10.

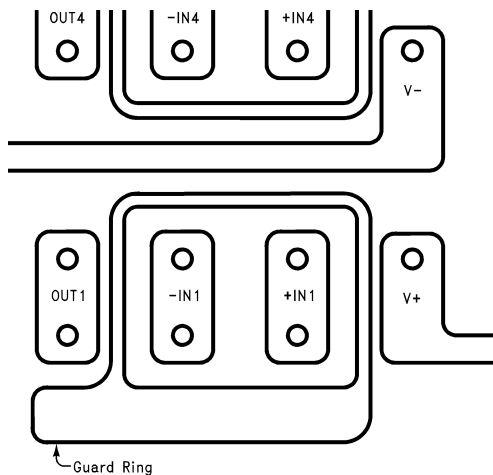


Figure 6. Example of Guard Ring in P.C. Board Layout (Using the LMC6024)

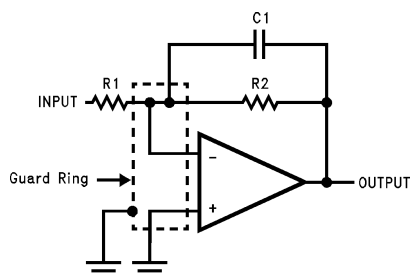


Figure 7. (a) Inverting Amplifier Guard Ring Connections

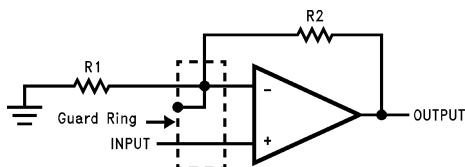


Figure 8. (b) Non-Inverting Amplifier Guard Ring Connections

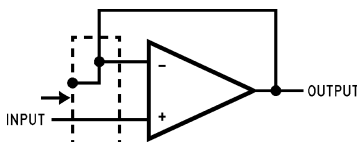


Figure 9. (c) Follower Guard Ring Connections

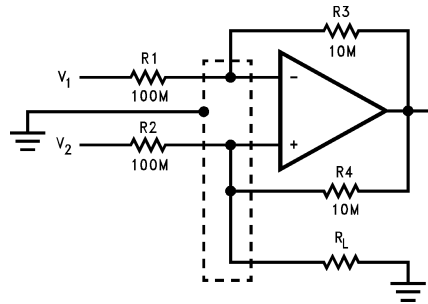
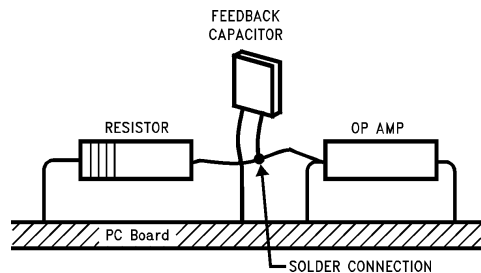


Figure 10. (d) Howland Current Pump Guard Ring Connections

The designer should be aware that when it is inappropriate to lay out a PC board for the sake of just a few circuits, there is another technique which is even better than a guard ring on a PC board: Don't insert the amplifier's input pin into the board at all, but bend it up in the air and use only air as an insulator. Air is an excellent insulator. In this case you may have to forego some of the advantages of PC board construction, but the advantages are sometimes well worth the effort of using point-to-point up-in-the-air wiring. See [Figure 11](#).



(Input pins are lifted out of PC board and soldered directly to components. All other pins connected to PC board.)

Figure 11. Air Wiring

BIAS CURRENT TESTING

The test method of [Figure 12](#) is appropriate for bench-testing bias current with reasonable accuracy. To understand its operation, first close switch S2 momentarily. When S2 is opened, then

$$I^- = \frac{dV_{OUT}}{dt} \times C2. \quad (1)$$

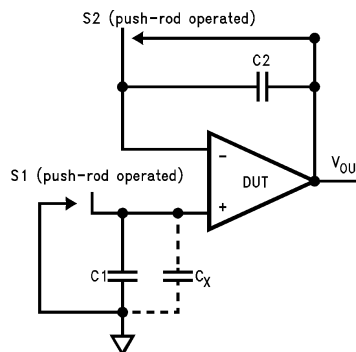


Figure 12. Simple Input Bias Current Test Circuit

A suitable capacitor for C2 would be a 5 pF or 10 pF silver mica, NPO ceramic, or air-dielectric. When determining the magnitude of I^- , the leakage of the capacitor and socket must be taken into account. Switch S2 should be left shorted most of the time, or else the dielectric absorption of the capacitor C2 could cause errors.

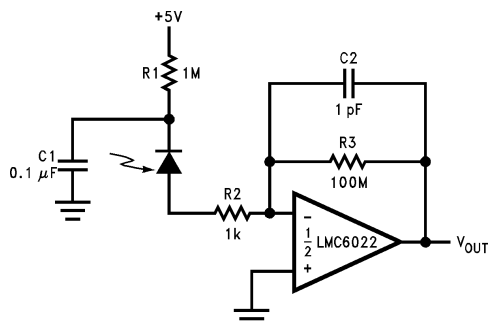
Similarly, if S1 is shorted momentarily (while leaving S2 shorted)

$$I^+ = \frac{dV_{OUT}}{dt} \times (C1 + C_x) \quad (2)$$

where C_x is the stray capacitance at the + input.

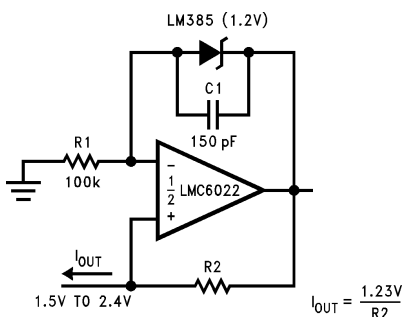
Typical Single-Supply Applications

($V^+ = 5.0 V_{DC}$)



Note: A 5V bias on the photodiode can cut its capacitance by a factor of 2 or 3, leading to improved response and lower noise. However, this bias on the photodiode will cause photodiode leakage (also known as its dark current).

Figure 13. Photodiode Current-to-Voltage Converter



(Upper limit of output range dictated by input common-mode range; lower limit dictated by minimum current requirement of LM385.)

Figure 14. Micropower Current Source

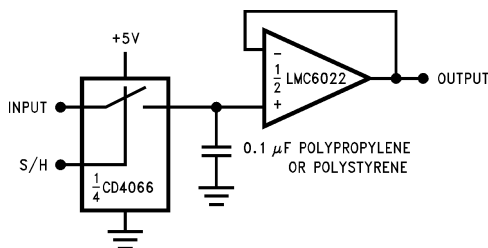
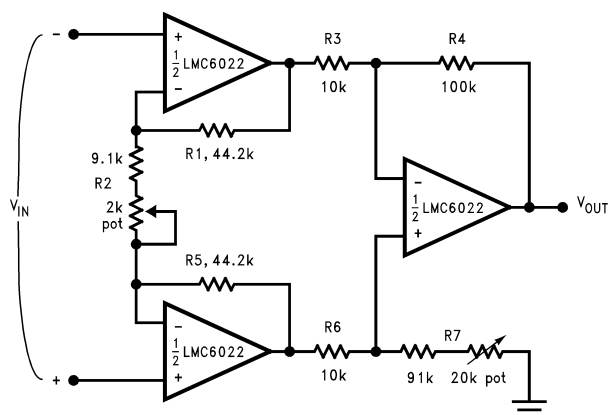


Figure 15. Low-Leakage Sample-and-Hold

(V₊ = 5.0 V_{DC})

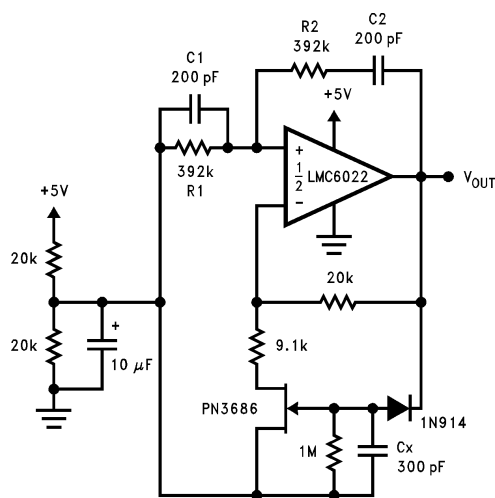
If R1 = R5, R3 = R6, and R4 = R7;

Then

$$\frac{V_{OUT}}{V_{IN}} = \frac{R2 + 2R1}{R2} \times \frac{R4}{R3}$$

∴ A_v ≈ 100 for circuit shown

For good CMRR over temperature, low drift resistors should be used. Matching of R3 to R6 and R4 to R7 affects CMRR. Gain may be adjusted through R2. CMRR may be adjusted through R7.

Figure 16. Instrumentation Amplifier

Oscillator frequency is determined by R1, R2, C1, and C2:

$$f_{OSC} = 1/2\pi RC$$

where R = R1 = R2 and C = C1 = C2.

Figure 17. Sine-Wave Oscillator

This circuit, as shown, oscillates at 2.0 kHz with a peak-to-peak output swing of 4.5V.

($V_+ = 5.0 V_{DC}$)

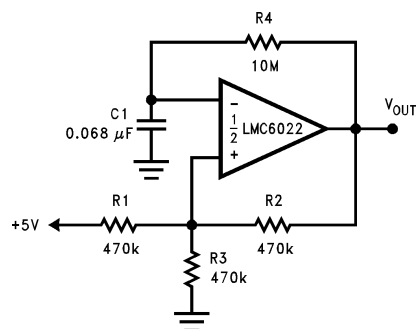


Figure 18. 1 Hz Square-Wave Oscillator

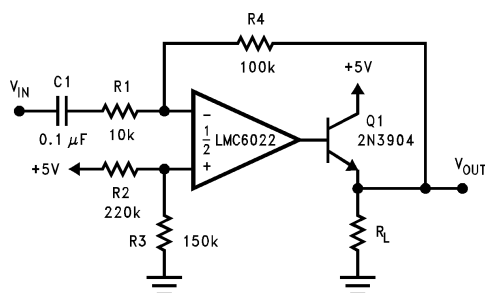
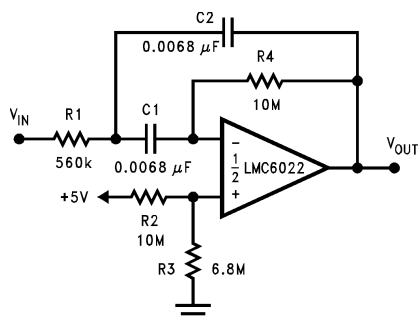
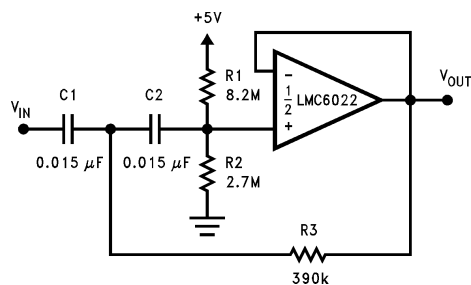


Figure 19. Power Amplifier

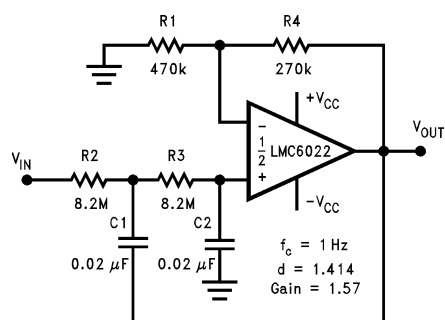
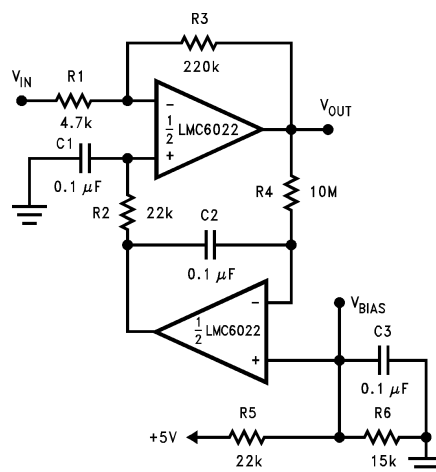


$f_0 = 10 \text{ Hz}$
 $Q = 2.1$
Gain = -8.8

Figure 20. 10 Hz Bandpass Filter

(V+ = 5.0 V_{DC})

$f_c = 10 \text{ Hz}$
 $d = 0.895$
 $\text{Gain} = 1$

Figure 21. 10 Hz High-Pass Filter (2 dB Dip)**Figure 22. 1 Hz Low-Pass Filter (Maximally Flat, Dual Supply Only)**

Gain = -46.8

Output offset voltage reduced to the level of the input offset voltage of the bottom amplifier (typically 1 mV), referred to V_{BIAS}.

Figure 23. High Gain Amplifier with Offset Voltage Reduction

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LMC6022IM	ACTIVE	SOIC	D	8	95	TBD	CU SNPB	Level-1-235C-UNLIM	
LMC6022IM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LMC6022IMX	ACTIVE	SOIC	D	8	2500	TBD	CU SNPB	Level-1-235C-UNLIM	
LMC6022IMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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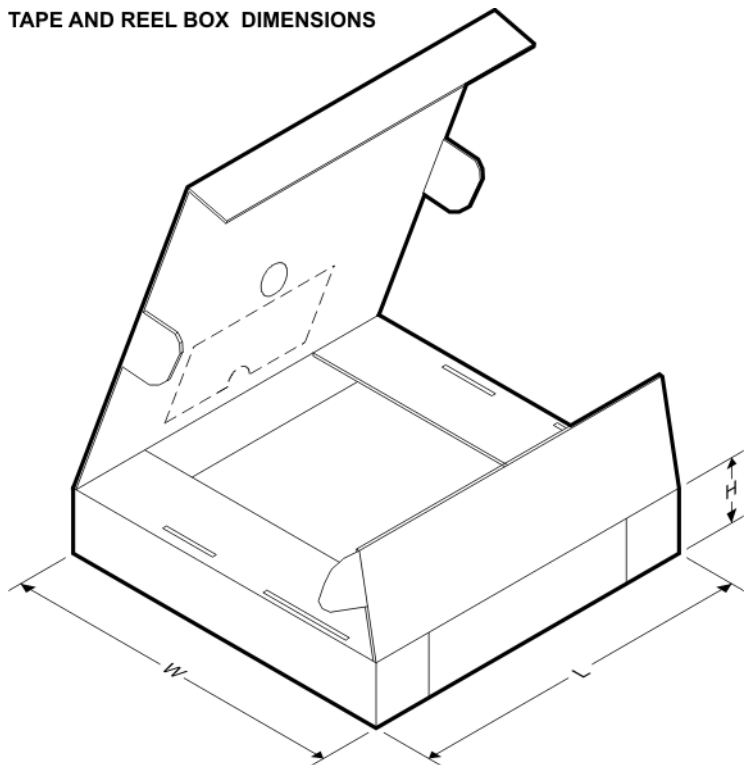
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMC6022IMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LMC6022IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

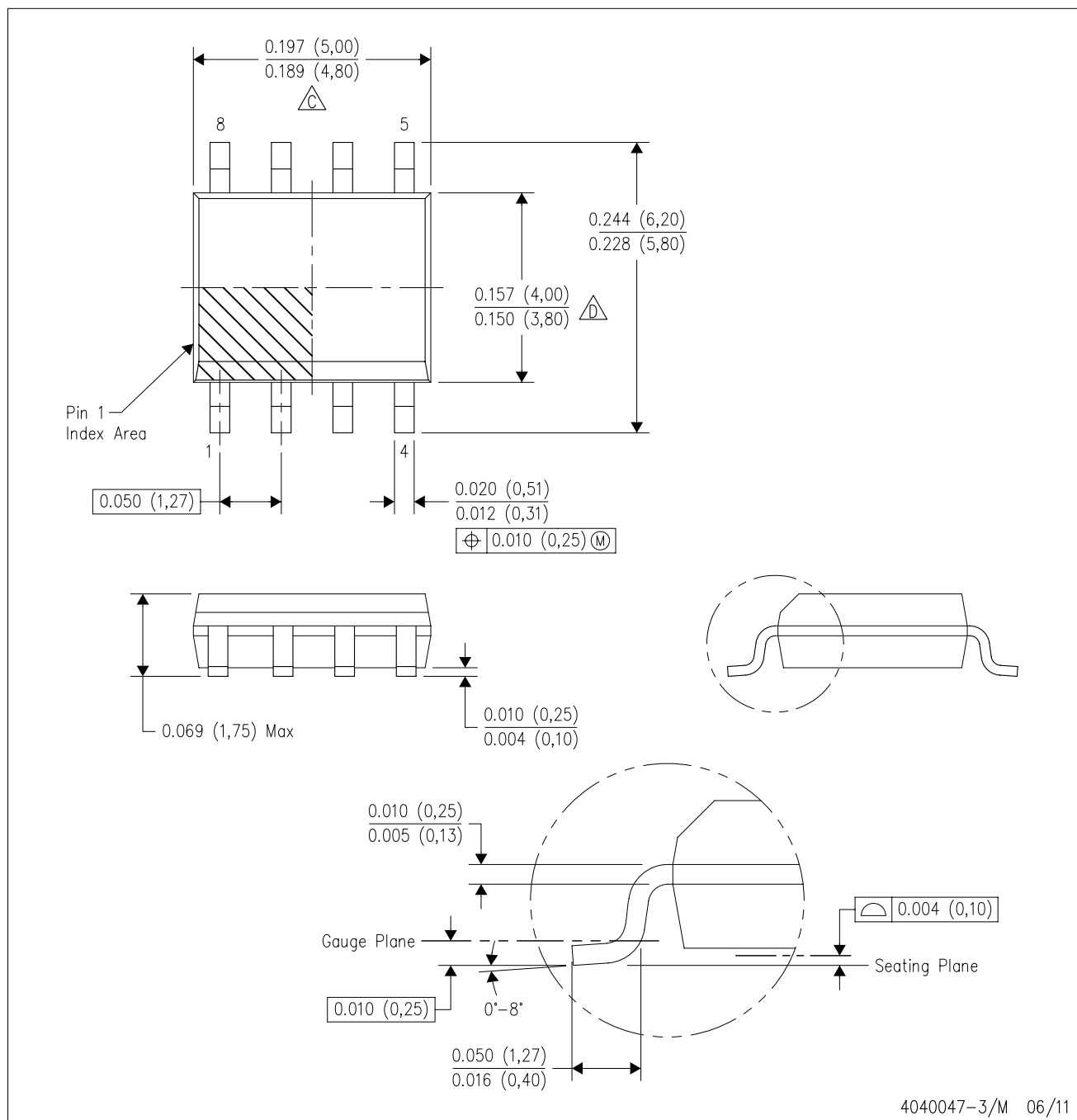


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMC6022IMX	SOIC	D	8	2500	349.0	337.0	45.0
LMC6022IMX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

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